Product Specification

Product:	Copper Paste For Filling Holes
Part Number:	25H-5901

Application Scope :
This product is designed for use in ceramic circuit fillers, including LTCC and LED applications.

Usage Conditions :

Substrate	Circuit of ceramic
Printing	screen print, silk-screen printing, screen printing
Leveling	Let it level at room temperature for 5-15 minutes (adjust time based on actual leveling conditions).
Drying	Furnace drying at 100-150°C for 10-15 minutes (the drying temperature should not exceed 300°C, and the drying time may be adjusted based on actual conditions.)
Firing Condition	The sintering temperature of the tunnel furnace under the nitrogen protective atmosphere is 830±10°C (recommended value) and the sintering time is 10-20 minutes. The sintering range can be adjusted between 800-850°C as needed, but the peak temperature must be maintained for at least 10 minutes.
Thinner	ST-1000

Characteristics :

1. Paste Characteristics :

Characteristic		Standard	Test Method And Conditions
1	Fineness	≤5μm	FOG test
2	Viscosity	200-580Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R, operating at 10rpm and 25±1°C, with adjustable viscosity according to user requirements.

2. Characteristics After Curing :

Under the 1-sintering condition, the film thickness is 8-12 μm.
Check fired film produced under the conditions specified in 1）, (Film thickness is 8-12μm.)

Characteristics		Standard	Test Method And Conditions
3	Resistivity	≤20mΩ/□	Test pattern 0.6mm×60mm

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-25°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.